

HGP12 High Thermally Conductive Gap Pad

BENEFITS AND FEATURES

- 12.0W/m.K thermal conductivity
- Good wetting to interfaces to reduce contact resistivity
- Soft to relief stress during assembling
- Easily compressed with low pressure due to its ultra-soft performance
- Low volatile (D3-D10 <100ppm)
- Low oil bleeding

OVERVIEW

Honeywell HGP12 provides 12.0W/m.K thermal conductivity with good wettability to many substrates. It helps to reduce thermal resistivity between interfaces. HGP12 is easily compressed at low pressure due to its ultra-soft characteristics. It fills multiple gaps with various tolerances. In addition, HGP12 is a low volatile and low oil bleeding grade, so it is fit for electronics applications which are sensitive to siloxane.

TYPICAL APPLICATIONS

- Optical module
- TIM for electronic components in Telecommunications
- High power lighting application, such as LCD, LED and projectors
- Auto electronics control units such as MCU

STORAGE & USE

Shelf Life: 12 months at 0-35°C, <65%RH

Property	HGP12	Test Method
Color	pink	By visual
Thermal Conductivity (W/m.K)	12.0	ASTM D5470
Thermal Impedance (in ² .K/W) (1mm@10psi)	0.13	ASTM D5470
Specific gravity	3.3	ASTM D792
Hardness (Shore 00)	30	ASTM D2240
Volatile content (TML%)	0.13	ASTM E595
Volatile content (CVCm%)	0.03	ASTM E595
D3-D10 (ppm)	<100	GC
Dielectric constant @1MHz	5.5	ASTM D150
Volume resistivity (Ohm.cm)	1.4x10 ¹⁴	ASTM D257
Flame retardancy	V-0	UL 94 equivalent

*Typical property data values should not be used as specifications

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